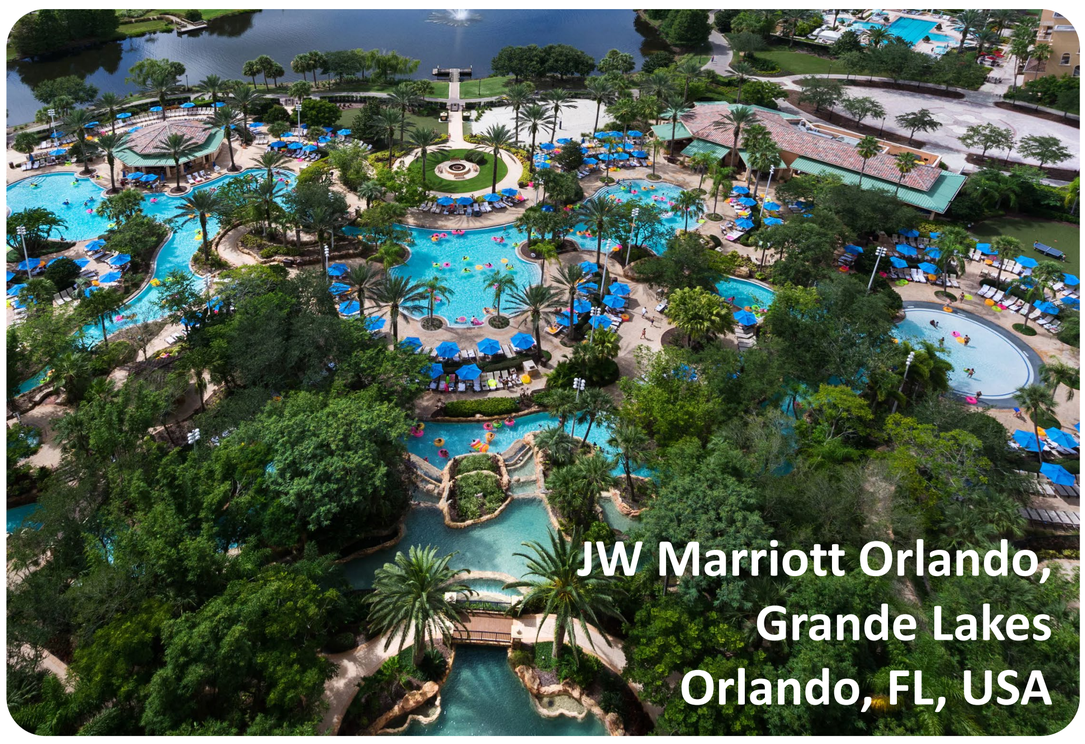
Abstracts Due: October 20, 2025

ITherm 2026
ORLANDO, FL

25th Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems

May 26 – 29, 2026



Important Dates

Abstract Deadline:	~~Oct. 6, 2025~~ **Oct. 20, 2025**
Notification of Acceptance:	~~Oct. 20, 2025~~ Nov. 3, 2025
Draft Paper Submission:	Jan. 5, 2026
Reviews Returned:	Feb. 2, 2026
Final Paper Submission:	Mar. 2, 2026

Call for Abstracts

The IEEE ITherm Conference is the leading international conference for scientific and engineering exploration of thermal, thermomechanical, and emerging technology issues associated with electronic devices, packages, and systems. ITherm 2026 will be a physical conference held along with the 76th ECTC. Joint ITherm/ECTC registrations will be available at a significant discount. All abstracts are followed by full papers to be peer reviewed and published in the IEEE Xplore ITherm proceedings. Student first authors will have the opportunity to apply for ITherm travel grants, to participate in the Student Poster and Networking Session. ITherm 2026 will also feature keynotes by prominent speakers, vendor exhibits, panel discussions, invited technology talks, ECTC/ITherm joint networking events and short courses, and a student design competition. Original papers are solicited in the following areas of interest:

Component-Level Thermal Management
- Advanced Packaging/HI Thermal Management
- Heat Pipes, Vapor Chambers and Thermosyphons
- Hotspot and Impingement Cooling
- Micro-gaps and Embedded Cooling
- RF and Power Electronics
- Single / Two-Phase Cold Plates and Heat Sinks
- Thermal Interface Materials and Heat Spreaders
- Thermal Management of Electric Machines

System-Level Thermal Management
- Air Cooling Techniques and Heat Exchangers
- Aerospace Thermal Management
- Automotive, Batteries and Thermal Storage
- Cryogenics and Refrigeration
- Immersion Cooling
- Liquid Cooling Solutions
- Transient Thermal Management

Mechanics and Reliability
- Accelerated Stress Testing and Modeling
- Advanced Packaging/HI Mechanics and Reliability
- Failure Mechanics, Fatigue and Damage Modeling
- Materials Characterization, Processing and Models
- Mechanics in Assembly and Manufacturing
- Measurement of Deformations, Strains and Stresses
- Shock, Drop and Vibrational Analysis
- Thermo-Mechanical Modeling and Simulation

Emerging Technologies and Fundamentals
- Additive Manufacturing and Topology Optimization
- Biomedical, Wearable, Flexible and Printed Electronics
- Boiling, Evaporation and Condensation
- Digital Twins
- DTCO, STCO, and Co-Design
- Measurement and Diagnostic Techniques
- Multi-scale, Multi-physics and Reduced Order Modeling
- Nanoscale and Transistor-Level Thermal Transport
- Next Generation Electronics
- Novel Materials and Fabrication Techniques
- Packaging and Interconnection Technologies
- Predictive Analytics, Machine Learning and AI
- Quantum Computing
- Thermoelectric and Peltier Devices

Data Centers
- Air Cooling Methods
- Carbon Emissions and Sustainability
- Economics and Scaling
- Hybrid and Novel Cooling Methods
- Liquid Cooling Methods
- Modeling, AI/ML Techniques, Control and Optimization
- Reliability and Failure Mitigation
- Performance Metrics, Standards and Regulatory Compliance

ITherm provides an opportunity for industrial and university participation in the form of financial support to ITherm 2026.
All contributors will be given strong recognition both onsite and in the conference materials.

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